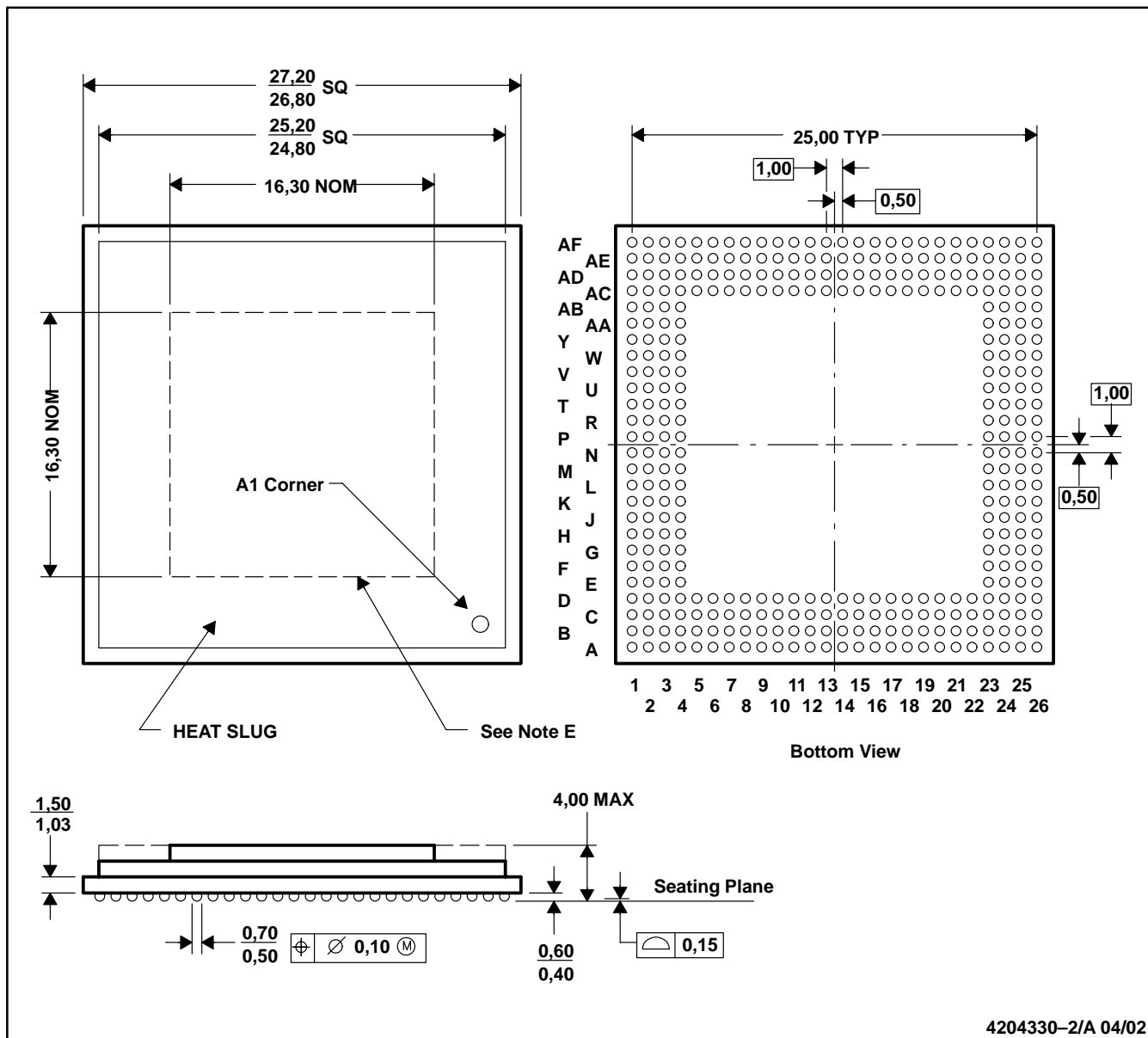


GPY (S-PBGA-N352)

PLASTIC BALL GRID ARRAY



4204330-2/A 04/02

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Thermally enhanced molded plastic package with a heat slug (HSL).
 - D. Flip chip application only.
 - E. Possible protrusion in this area, but within 4,00 max package height specification.
 - F. Falls within JEDEC MO-151/AAL-1

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Mailing Address:

Texas Instruments
Post Office Box 655303
Dallas, Texas 75265